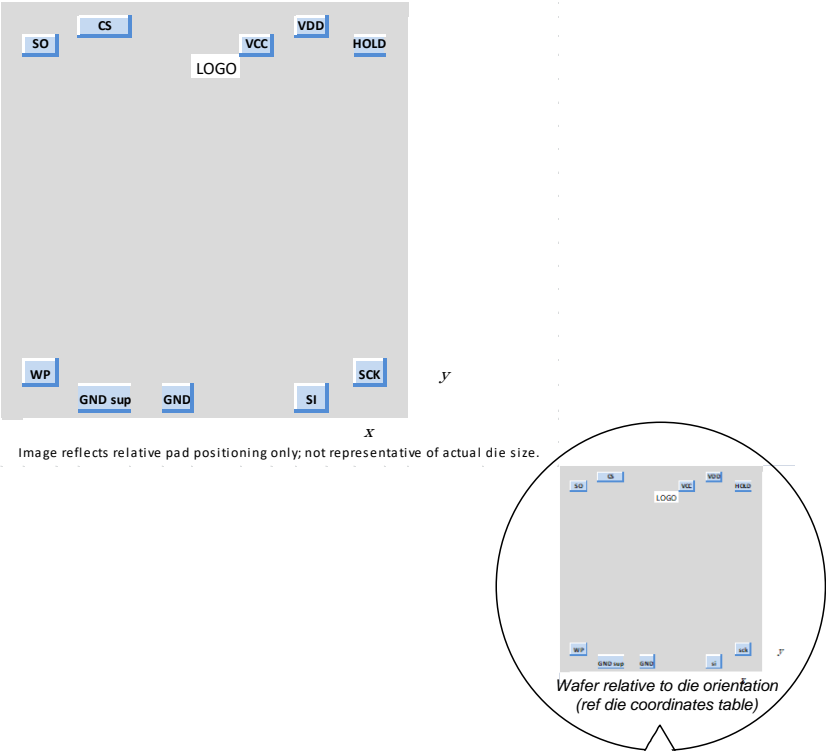


WAFER PRODUCT DATASHEET (ADDENDUM)

Product	AT25SF041-DWF and AT25SF041-DWFHT																																															
Description	4Mbit, Standard Serial Flash, 2.5V – 3.6V VCC																																															
Die Map	 <p>Image reflects relative pad positioning only; not representative of actual die size.</p> <p>Wafer relative to die orientation (ref die coordinates table)</p>																																															
Die Size & Pad Coordinates	<table border="1"> <thead> <tr> <th></th> <th>X (μm)</th> <th>Y (μm)</th> </tr> </thead> <tbody> <tr> <td>Die Size</td> <td>1310</td> <td>1224</td> </tr> <tr> <td>Scribe Line Width</td> <td>60</td> <td>60</td> </tr> <tr> <td>Die Step</td> <td>1370</td> <td>1284</td> </tr> <tr> <td>Pad Opening</td> <td>65</td> <td>70</td> </tr> <tr> <td>CS</td> <td>217.9</td> <td>1164.7</td> </tr> <tr> <td>SO</td> <td>76.7</td> <td>1139.7</td> </tr> <tr> <td>WP</td> <td>54.2</td> <td>86.3</td> </tr> <tr> <td>GND SUP</td> <td>139.2</td> <td>63.7</td> </tr> <tr> <td>GND</td> <td>224.2</td> <td>63.7</td> </tr> <tr> <td>SI</td> <td>1118.4</td> <td>60.3</td> </tr> <tr> <td>SCK</td> <td>1225.4</td> <td>76.7</td> </tr> <tr> <td>HOLD</td> <td>1235.5</td> <td>1141.6</td> </tr> <tr> <td>VDD</td> <td>1136.3</td> <td>1164.3</td> </tr> <tr> <td>VCC</td> <td>1046.3</td> <td>1143.8</td> </tr> </tbody> </table>				X (μm)	Y (μm)	Die Size	1310	1224	Scribe Line Width	60	60	Die Step	1370	1284	Pad Opening	65	70	CS	217.9	1164.7	SO	76.7	1139.7	WP	54.2	86.3	GND SUP	139.2	63.7	GND	224.2	63.7	SI	1118.4	60.3	SCK	1225.4	76.7	HOLD	1235.5	1141.6	VDD	1136.3	1164.3	VCC	1046.3	1143.8
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Technical Details	
Adesto Product Family	Standard Flash
Density	4 Mbit
Operating Vcc	2.5V - 3.6V
ESD	JESD22-A114
Delivery Option	Wafer- unsawn
Wafer Size (mm)	300 mm
Process Geometry (nm)	90 nm
Die ID	W016
Wafer Map	Electronic- text file
Manufacturing Facility	XMC
Wafer Thickness (µm) Maximum	800
Back Grind Options	None / Contact Adesto
Back Plane Connection	Floating / Not Required
Backside preparation / metallization	None
Bond wire qualified	AU <input checked="" type="checkbox"/> CU <input type="checkbox"/> AG <input type="checkbox"/>
Passivation Material	PETEOS + SiON
Passivation Thickness (Å)	11000
Bond Pad Material	TaN/AlCu
Bond Pad Thickness (Å)	10300
Good Die per Wafer	Contact Adesto (AT25SF041-DWF) ¹
Good Die per Wafer	Contact Adesto (AT25SF041-DWFHT) ¹
Active Circuits underneath the bond pad	Yes

¹ Average value; subject to change without notice.

Part Number Ordering Code ²	Operating Temperature Range	Functional Specification
AT25SF041-DWF	-40°C to 85°C	http://www.adestotech.com/wp-content/uploads/DS-AT25SF041_044.pdf
AT25SF041-DWFHT	-40°C to 125°C	http://www.adestotech.com/wp-content/uploads/DS-AT25SF041-HRADD.pdf

² Handle product in accordance with UV and ESD precautions.

Adesto Technologies Corporation

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Revision Level – Release Date	History
A – September 2015	Initial release.
B – August 2016	Added high temperature part number.
C – August 2017	Updated address and contact information.

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